

20 V, P-channel Trench MOSFET

7 July 2020

### 1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in a small SOT457 (SC-74) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

### 2. Features and benefits

- Low threshold voltage
- Extended temperature range T<sub>i</sub> = 175 °C
- Very fast switching
- Trench MOSFET technology
- ElectroStatic Discharge (ESD) protection > 1000 V HBM (class H1C)
- AEC-Q101 qualified

### 3. Applications

- Relay driver
- High-speed line driver
- High-side load switch
- Switching circuits

### 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Мах	Unit
V <sub>DS</sub>	drain-source voltage	T <sub>j</sub> = 25 °C		-	-	-20	V
V <sub>GS</sub>	gate-source voltage			-12	-	12	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 25 °C	[1]	-	-	-4.7	А
Static charac	cteristics	·					
R <sub>DSon</sub>	drain-source on-state resistance	V <sub>GS</sub> = -4.5 V; I <sub>D</sub> = -4.7 A; T <sub>j</sub> = 25 °C		-	43	50	mΩ

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.

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### 5. Pinning information

Table 2. F	Pinning infor	mation		
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	D	drain		D
2	D	drain		
3	G	gate		G ↓ ↓ ↓ ↓
4	S	source	SC-74; TSOP6 (SOT457)	
5	D	drain		
6	D	drain		s s
				017aaa259

### 6. Ordering information

#### Table 3. Ordering information

Type number	Package					
	Name	Description	Version			
PMN40XPEA	SC-74; TSOP6	plastic, surface-mounted package (SC-74; TSOP6); 6 leads	SOT457			

### 7. Marking

#### Table 4. Marking codes

Type number	Marking code
PMN40XPEA	6F

### 8. Limiting values

#### Table 5. Limiting values

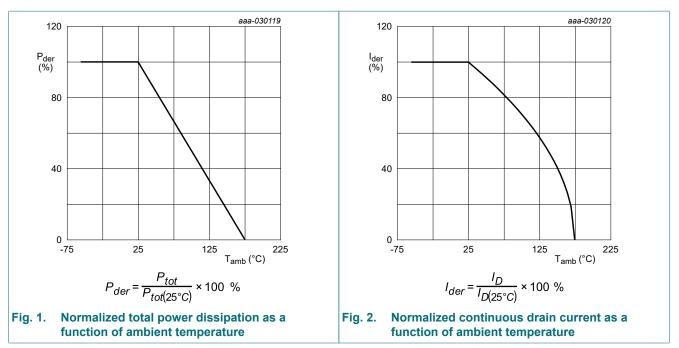
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>DS</sub>	drain-source voltage	T <sub>j</sub> = 25 °C		-	-20	V
V <sub>GS</sub>	gate-source voltage			-12	12	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 25 °C	[1]	-	-4.7	А
		V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 100 °C	[1]	-	-3	А
I <sub>DM</sub>	peak drain current	$T_{amb}$ = 25 °C; single pulse; $t_p \le 10 \ \mu s$		-	-19	А
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C	[2]	-	660	mW
			[1]	-	1.7	W
		T <sub>sp</sub> = 25 °C		-	7.5	W
Tj	junction temperature			-55	175	°C
T <sub>amb</sub>	ambient temperature			-55	175	°C
T <sub>stg</sub>	storage temperature			-65	175	°C
Source-drain	n diode					
ls	source current	T <sub>amb</sub> = 25 °C	[1]	-	-1.7	А
ESD maximu	um rating					_
V <sub>ESD</sub>	electrostatic discharge voltage	НВМ	[3]	-	1000	V
Avalanche r	uggedness			1		
E <sub>DS(AL)S</sub>	non-repetitive drain- source avalanche energy	$ T_{j(init)} = 25 \text{ °C}; I_D = -1.5 \text{ A}; \text{ DUT in}$ avalanche (unclamped)		-	15	mJ

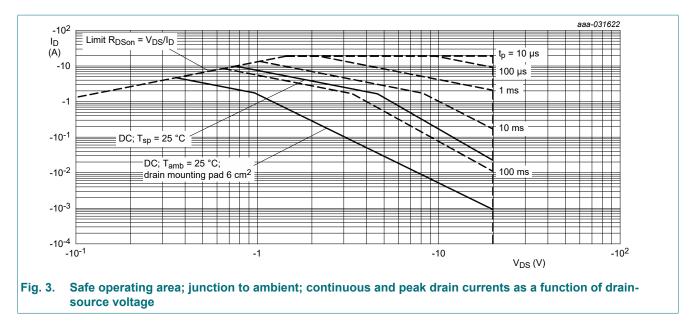
[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[3] Measured between all pins.



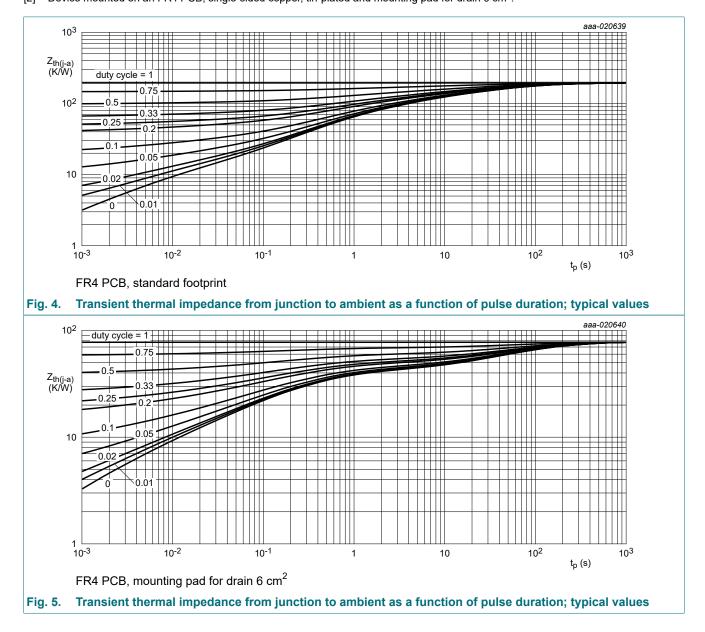
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### 9. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
ui(j-a)	thermal resistance from	in free air	[1]	-	195	225	K/W
	junction to ambient		[2]	-	78	90	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point			-	15	20	K/W

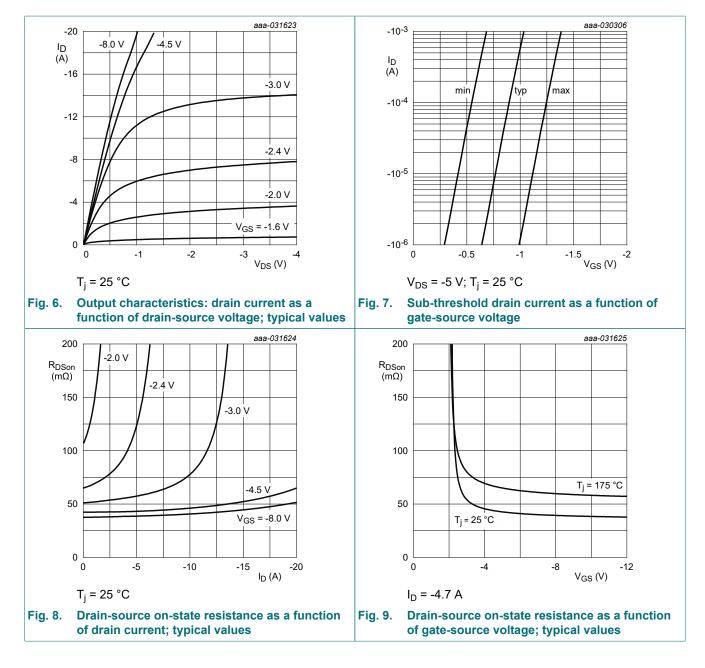
Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
 Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.



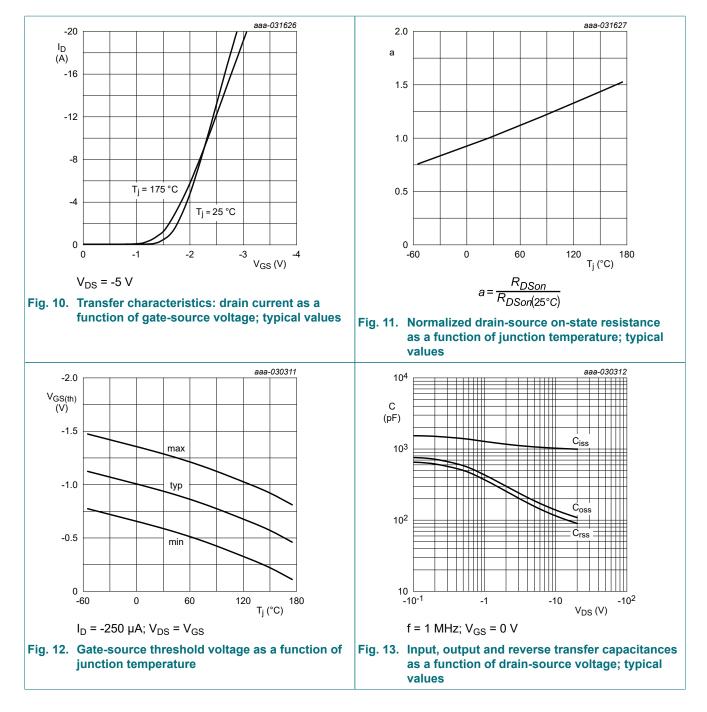
### **10. Characteristics**

Symbol	Parameter	Conditions	Min	Тур	Мах	Unit
Static chara	cteristics					
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	I <sub>D</sub> = -250 μA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	-20	-	-	V
V <sub>GSth</sub>	gate-source threshold voltage	I <sub>D</sub> = -250 μA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = 25 °C	-0.6	-0.95	-1.3	V
I <sub>DSS</sub>	drain leakage current	V <sub>DS</sub> = -20 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	-1	μA
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = -12 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	-10	μA
		V <sub>GS</sub> = 12 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	10	μA
		V <sub>GS</sub> = -4.5 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	-2	μA
		V <sub>GS</sub> = 4.5 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	2	μA
R <sub>DSon</sub>	drain-source on-state	V <sub>GS</sub> = -8 V; I <sub>D</sub> = -4.7 A; T <sub>j</sub> = 25 °C	-	39	46	mΩ
	resistance	V <sub>GS</sub> = -8 V; I <sub>D</sub> = -4.7 A; T <sub>j</sub> = 175 °C	-	59	70	mΩ
		V <sub>GS</sub> = -4.5 V; I <sub>D</sub> = -4.7 A; T <sub>j</sub> = 25 °C	-	43	50	mΩ
		V <sub>GS</sub> = -2.5 V; I <sub>D</sub> = -2 A; T <sub>j</sub> = 25 °C	-	64	78	mΩ
9 <sub>fs</sub>	forward transconductance	V <sub>DS</sub> = -10 V; I <sub>D</sub> = -4.7 A; T <sub>j</sub> = 25 °C	-	9.5	-	S
R <sub>G</sub>	gate resistance	f = 1 MHz	-	21	-	Ω
Dynamic ch	aracteristics					
Q <sub>G(tot)</sub>	total gate charge	V <sub>DS</sub> = -10 V; I <sub>D</sub> = -5.8 A; V <sub>GS</sub> = -4.5 V;	-	10.6	16	nC
Q <sub>GS</sub>	gate-source charge	T <sub>j</sub> = 25 °C	-	2.1	-	nC
Q <sub>GD</sub>	gate-drain charge		-	3.6	-	nC
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = -10 V; f = 1 MHz; V <sub>GS</sub> = 0 V;	-	1025	-	pF
C <sub>oss</sub>	output capacitance	T <sub>j</sub> = 25 °C	-	137	-	pF
C <sub>rss</sub>	reverse transfer capacitance	] [	-	113	-	pF
t <sub>d(on)</sub>	turn-on delay time	V <sub>DS</sub> = -10 V; I <sub>D</sub> = -5.8 A; V <sub>GS</sub> = -4.5 V;	-	6	-	ns
t <sub>r</sub>	rise time	$R_{G(ext)} = 6 \Omega; T_j = 25 °C$	-	17	-	ns
t <sub>d(off)</sub>	turn-off delay time		-	23	-	ns
t <sub>f</sub>	fall time	1	-	19	-	ns
Source-drai	n diode	· ·	i			
V <sub>SD</sub>	source-drain voltage	I <sub>S</sub> = -1.7 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-0.8	-1.2	V
t <sub>rr</sub>	reverse recovery time	$I_{S}$ = -2 A; dI <sub>S</sub> /dt = 100 A/µs; V <sub>GS</sub> = 0 V;	-	17	-	ns
Q <sub>r</sub>	recovered charge	V <sub>DS</sub> = -10 V; T <sub>j</sub> = 25 °C	-	5	_	nC

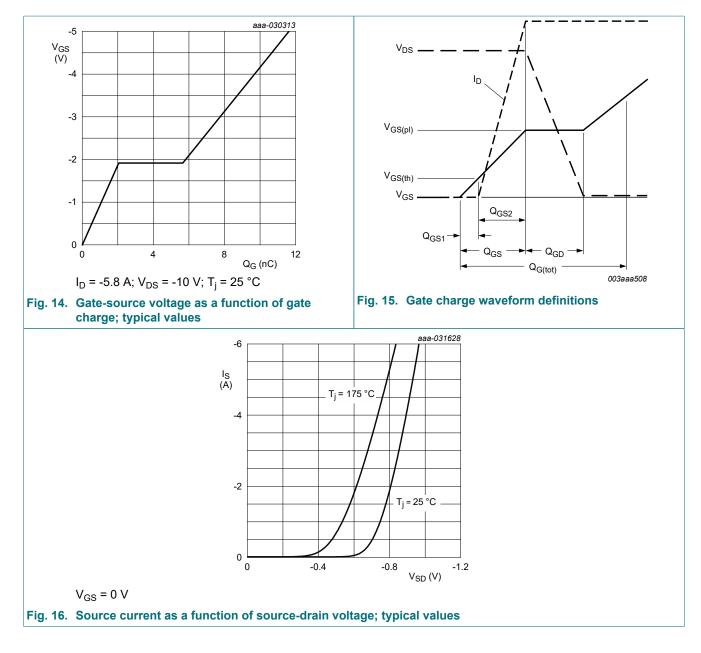
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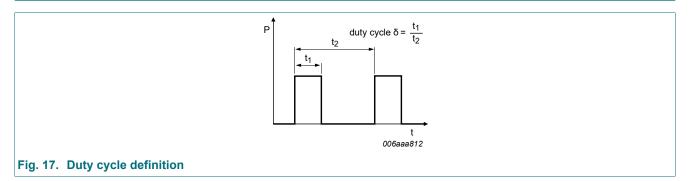
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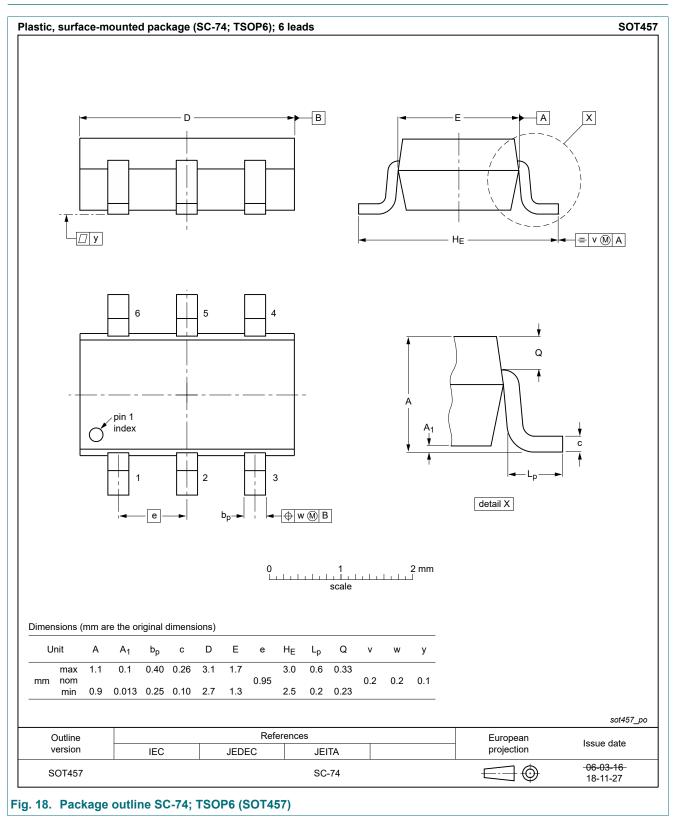
### **11. Test information**



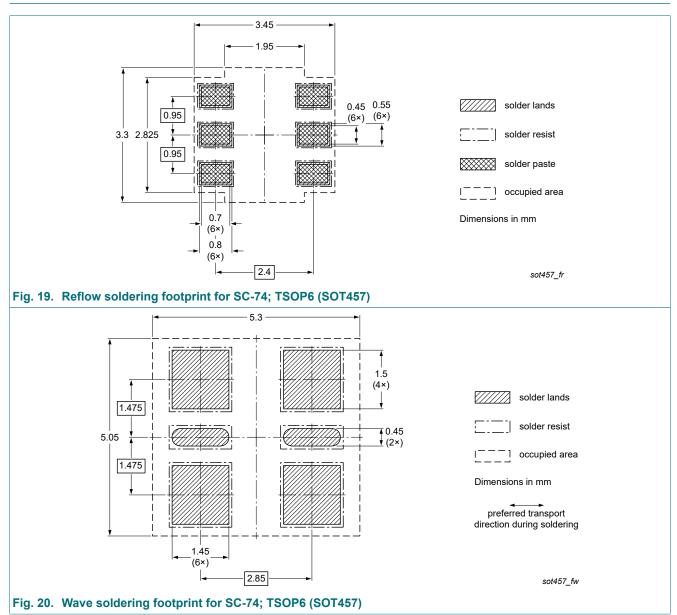
#### **Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101* - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

### 12. Package outline



### 13. Soldering



### 14. Revision history

Table 8. Revision history						
Data sheet ID	Release date	Data sheet status	Change notice	Supersedes		
PMN40XPEA v.1	20200707	Product data sheet	-	-		

### 15. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

 Please consult the most recently issued document before initiating or completing a design.

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### Contents

1. General description	1
2. Features and benefits	1
3. Applications	1
4. Quick reference data	1
5. Pinning information	2
6. Ordering information	2
7. Marking	2
8. Limiting values	3
9. Thermal characteristics	5
10. Characteristics	6
11. Test information	10
12. Package outline	11
13. Soldering	
14. Revision history	13
15. Legal information	

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